



Material Content Data Sheet



Sales Product Name		BSS314PE H6327		Issued		22. October 2018		
MA#		MA000949852						
Package		PG-SOT23-3-5		Weight*		9.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.003	0.03		336	
	noble metal	gold	7440-57-5	0.012	0.13		1304	
	inorganic material	silicon	7440-21-3	0.187	1.99	2.15	19897	21537
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		321	
	non noble metal	chromium	7440-47-3	0.009	0.10		964	
	non noble metal	copper	7440-50-8	3.000	32.00	32.14	320019	321368
wire	non noble metal	copper	7440-50-8	0.043	0.46	0.46	4608	4608
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6062	
	plastics	epoxy resin	-	1.222	13.03		130331	
	inorganic material	silicondioxide	60676-86-0	4.405	46.98	60.62	469797	606190
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	15961	15961
plating	noble metal	silver	7440-22-4	0.284	3.03	3.03	30336	30336
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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